Plaskon PPF-165

Epoxy; Epoxide

Cookson Electronics - Semiconductor Products

Message:

This material is a conventional epoxy molding compound specifically formulated for semiconductor devices which are molded with preplated leadframes. It increases semiconductor manufacturing productivity and reduces production costs.

General Information			
Features	Semi-conductive Low viscosity Fast curing		
Forms	Liquid		
Processing Method	Resin transfer molding		
Physical	**Nominal Value**	**Unit**	**Test Method**
Specific Gravity	1.80	g/cm³	ASTM D792
Molding Shrinkage - Flow	0.30	%	ASTM D955
Mechanical	**Nominal Value**	**Unit**	**Test Method**
Flexural Modulus	1.52	MPa	ASTM D790
Flexural Strength	0.0124	MPa	ASTM D790
Thermal	**Nominal Value**	**Unit**	**Test Method**
Glass Transition Temperature	130	°C	ASTM E1356
CLTE - Flow	2.1E-5	cm/cm/°C	ASTM D696
Electrical	**Nominal Value**	**Unit**	**Test Method**
Volume Resistivity	5.0E+15	ohms·cm	ASTM D257
Dielectric Strength	16	kV/mm	ASTM D149
Dielectric Constant (1 kHz)	3.50		ASTM D150
Dissipation Factor (1 kHz)	3.0E-3		ASTM D150
Arc Resistance	180	sec	ASTM D495
Flammability	**Nominal Value**	**Unit**	**Test Method**
Flame Rating (3.18 mm)	V-0		UL 94
Oxygen Index	30	%	ASTM D2863
Additional Information			

Recommended Storage Temperature: 5°CLife @ 5°C, defined as not more than 40% loss of spiral flow based on original values.: 24 monthsLife @ 21°C, defined as not more than 40% loss of spiral flow based on original values.: 5 daysLife @ 35°C, defined as not more than 40% loss of spiral flow based on original values.: 2 daysSpiral Flow, 165°C, 1000 psi: 72 cmSpiral Flow, 175°C, 1000 psi: 72 cmAutomatic Orifice Viscosity, 175°C, Shear Rate is 100000 sec-1, 1 mm die length, 1/2 mm diameter: 11 poiseAutomatic Orifice Viscosity, 165°C, Shear Rate is 100000 sec-1, 1 mm die length, 1/2 mm diameter: 17 Pascal secRam Follower Gel Time, 165°C: 18 secRam Follower Gel Time, 175°C: 12 secAsh Content: 72 %Hydrolyzable Halides: <1 ppmCull Hot Hardness, Shore D, 90 sec, 165°C: 80Cull Hot Hardness, Shore D, 90 sec, 175°C: 90Gangpot Hot Hardness, Shore D, 30 sec, 165°C: 70Arc Resistance, 110v AC180 secAll test specimens are transfer molded and post cured for 4 hours at 175°CThe following information was transfer molded and post cured for 15 minutes at 175°C
Glass Transition Temperature Tg: 157°C
Linear Thermal Expansion, Alpha 1: 21 cm^-6/cm/°C
Linear Thermal Expansion, Alpha 2: 64 cm^-6/cm/°C
The following information was transfer molded and post cured for 15 minutes at 165°C
Glass Transition Temperature Tg: 157°C
Linear Thermal Expansion, Alpha 1: 21 cm^-6/cm/°C
Linear Thermal Expansion, Alpha 2: 67 cm^-6/cm/°C
Thermal Conductivity14 cal/cm-sec-°C
The following information was transfer molded and post cured for 30 seconds at 175°C
Glass Transition Temperature Tg: 130°C
Linear Thermal Expansion, Alpha 1: 21 cm^-6/cm/°C
Linear Thermal Expansion, Alpha 2: 64 cm^-6/cm/°C
The following information was transfer molded and post cured for 30 seconds at 165°C
Glass Transition Temperature Tg: 135°C
Linear Thermal Expansion, Alpha 1: 21 cm^-6/cm/°C
Linear Thermal Expansion, Alpha 2: 67 cm^-6/cm/°C

Injection instructions

Conventional Resin TransferMolding:
Preheat Temperature: 85 to 95°C
Molding Temperature: 165 to 175°C
Molding Pressure: 500 to 1000 psi
Cycle Time, 175°C: 30 to 60 sec
Cycle Time, 165°C: 60 to 90 sec
Cure Time, 177°C: 0 to 15min
Post Mold Cure Time, 175°C: 0 to 15 hr
Gangpot Resin TransferMolding:
Preheat Temperature: 165°C
Molding Temperature: 35 to 70°C
Molding Pressure: 500 to 1000 psi
Cycle Time, 175°C: <30 sec
Cycle Time, 165°C: 40 sec
Post Mold Cure Time, 175°C: 0 to 15 hr
Post Mold Cure Time, 165°C: 0 to 15 hr

Recommended distributors for this material

Susheng Import & Export Trading Co.,Ltd.

Tel: +86 21 5895 8519

Phone: +86 13424755533

Email: sales@su-jiao.com

No. 215, Lianhe North Road, Fengxian District, Shanghai, China


WECHAT